







Delivering Value through Innovation and Dedication





ThunderClad 2

Core: TU-883 Prepreg: TU-883P

ThunderClad 2 (TU-883) is a very low loss category material based on a high performance resin. This material is reinforced with regular woven E-glass and designed with very low dielectric constant and dissipation factor resin system for high speed low loss, radio frequency and wireless applications. ThunderClad 2 material is suitable for environmental protection lead free process and also compatible with FR-4 processes. ThunderClad 2 laminates also exhibit excellent moisture resistance, improved CTE, superior chemical resistance, thermal stability and CAF resistance.

Applications

- Radio frequency
- Backplane, High performance computing
- Line cards, Storage
- Servers, Telecom, Base station, Office Routers

Performance and Processing Advantages

- Excellent electrical properties
- Dielectric constant less than 4.0
- Dissipation factor less than 0.005
- Stable and flat Dk/Df performance over frequency and temperature
- Compatible with modified FR-4 processes
- Excellent moisture resistance and Lead Free reflow process compatible
- Improved z-axis thermal expansion
- Anti-CAF capability
- · Excellent through-hole and soldering reliability
- Halogen Free

Industry Approvals

- IPC-4101 Type Designation: /134
- IPC-4101/134 Validation Services QPL Certified
- UL File Number : E189572
- ANSI Grade : No-ANSI
- Flammability Rating: 94V-0
- Maximum Operating Temperature: 160°C

Standard Availability

- Thickness: 0.002"[0.05mm] to 0.062" [1.58mm], available in sheet or panel form
- Copper Foil Cladding: 1/3 to 5 oz for built-up & double sides
- Prepregs: Available in roll or panel form
- Glass Styles: 106, 1080, 3313, 2116 and other prepreg grades are available upon request







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Very Low Loss and High Thermal Reliability Laminate and Prepreg Lead Free

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	Typical Values	Test Condition	SPEC
Thermal			
Tg (DMA) Tg (TMA) Td (TGA)	220 °C 170 °C 420 °C	E-2/105+des	N/A
CTE z-axis α1 CTE z-axis α2 CTE z-axis	35 ppm/°C 240 ppm/°C 2.5 %	Pre-Tg Post-Tg 50 to 260°C	< 60 ppm/°C < 300 ppm/°C < 3.0%
Thermal Stress, Solder Float, 288°C	> 60 sec	A	> 10 sec
T-260 T-288 T-300	> 60 min > 60 min > 60 min	E-2/105+des	> 30 min > 15 min
Flammability	94V-0	E-24/125+des	94V-0
Electrical			
Permittivity (RC63%) 1GHz (SPC method) 5GHz (SPC method) 10GHz (SPC method)	3.60 3.58 3.57	C-24/23/50	N/A
Loss Tangent (RC63%) 1GHz (SPC method) 5GHz (SPC method) 10GHz (SPC method)	0.0030 0.0037 0.0046	C-24/23/50	N/A
Volume Resistivity	> 10 ¹⁰ MΩ·cm	C-96/35/90	> 10 ⁶ MΩ • cm
Surface Resistivity	$> 10^8 M\Omega$	C-96/35/90	$> 10^4\text{M}\Omega$
Electric Strength	> 40 KV/mm	-	> 30 KV/mm
Dielectric Breakdown Voltage	> 50 KV	-	> 40 KV
Mechanical			
Young's Modulus Warp Direction Fill Direction	28 GPa 26 GPa	A	N/A
Flexural Strength Lengthwise Crosswise	> 60,000 psi > 50,000 psi	A A	> 60,000 psi > 50,000 psi
Peel Strength, 1.0 oz. Cu foil	4~6 lb/in	A	> 4 lb/in
Water Absorption	0.08 %	E-1/105+des+D-24/23	< 0.8 %

NOTE:

- $1.\ Property\ values\ are\ for\ information\ purposes\ only\ and\ not\ intended\ for\ specification.$
- 2. Any sales of these products will be governed by the terms and conditions of the agreement under which they are sold.
- 3. This product is based on a patent pending technology.

